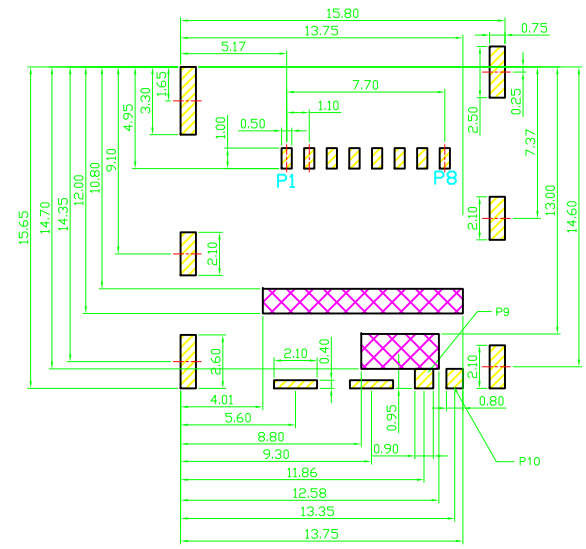
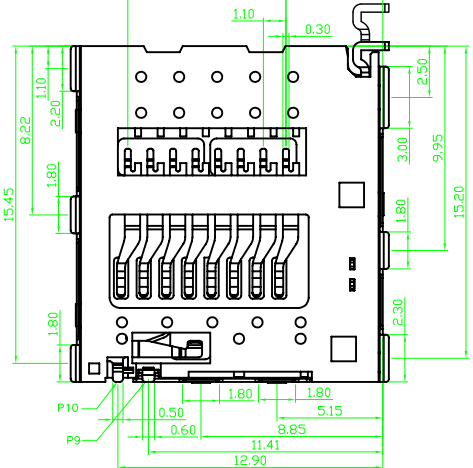
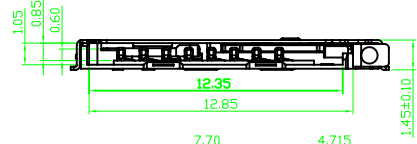
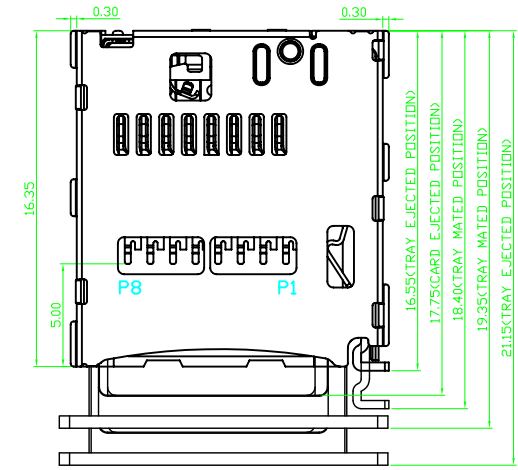


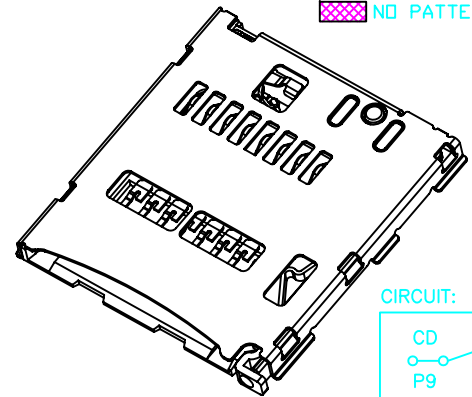
更改 REV	修改内容 MODIFICATION
A	ECXXXXX



RECOMMENDED PCB PATTERN LAYOUT

TOLERANCE: ±0.05

- PAD AREA
- NO PATTERN AREA OR PANEL OPENING



CIRCUIT:



NOTES :

- MATERIAL :
 - HOUSING:LCP UL94 V-0, BLACK COLOR.
 - SHELL: STAINLESS STEEL SUS.
 - CONTACT: COPPER ALLOY.
- FINISH :
 - CONTACT: GOLD PLATING ON CONTACT AREA, 1u" GOLD MIN ON SOLDERTAL AREA. 50u" MIN NICKEL PLATING OVERALL.
 - SHELL: 30u" MIN NICKEL PLATING OVERALL. Au 1u"MIN ON SOLDERTAL AREA.
- ELECTICAL CHARACTERISTICS:
 - OPERATING VOLTAGE : 100V AC(rms)/DC.
 - CURRENT RATING : 0.5 A.
 - OPERATING TEMPERATURE: -25°C~+85°C.
 - CONTACT RESISTANCE: 100 m OHMS MAX.
 - INSULATION RESISTANCE: 1000M OHMS MIN. AT 250VDC.
 - DIELECTRIC WITHSTANDING VOLTAGE:500 VAC/1MINUTE.

DETCT SWITCH FUNCTION:

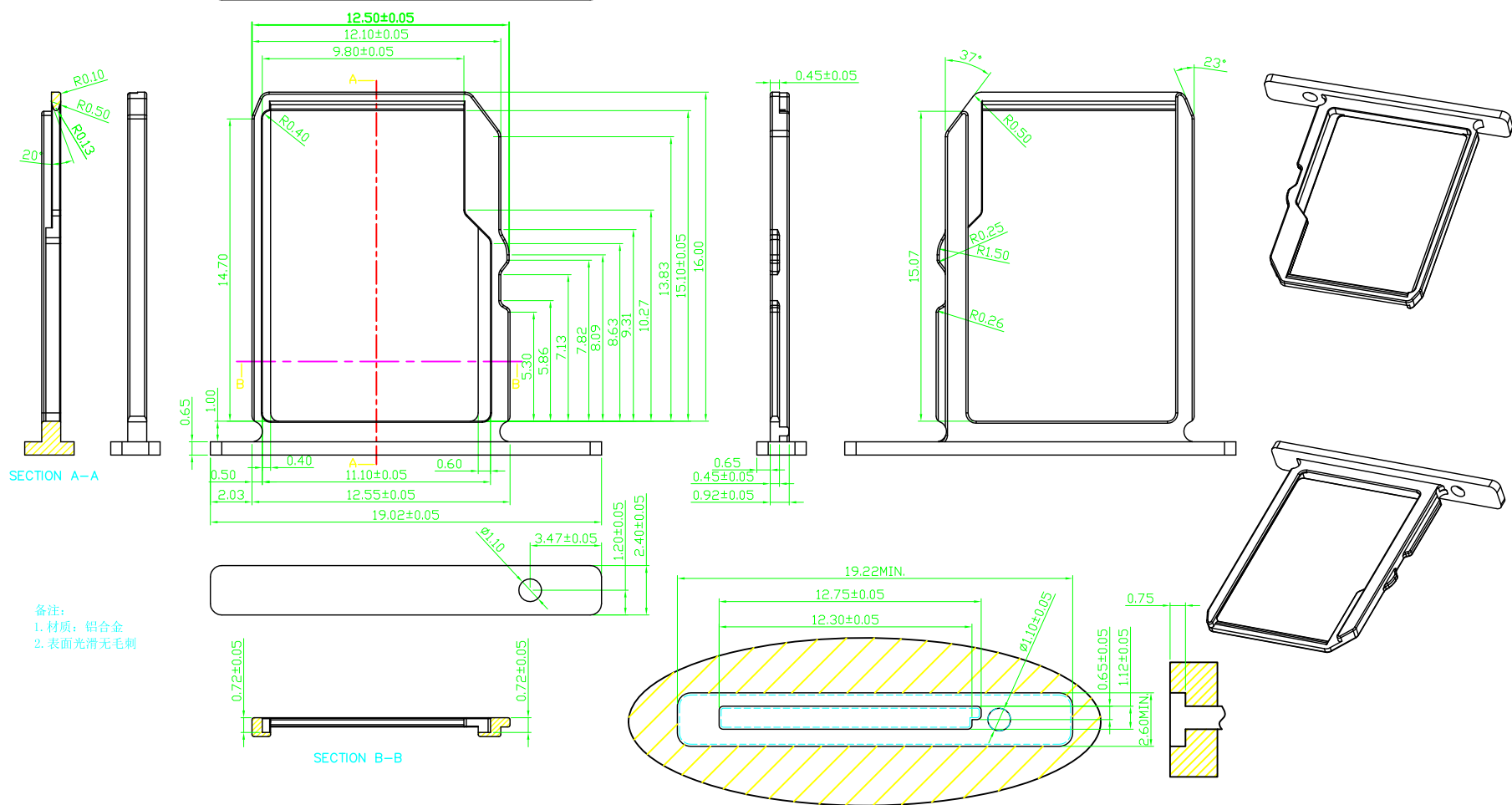
NO TRAY	OPEN
TRAY EJECTED POSITION	OPEN
TRAY MATED POSITION	CLOSE

Micro-SD CARD			
Pin No.	NAME	TYPE	DESCRIPTION
P1	DAT 2	I/O/PP	Date Line(bit2)
P2	CD/DAT 3	I/O/PP	Card Detect/Date Line(bit3)
P3	CMD	PP	Command Response
P4	VDD	S	Supply Voltage
P5	CLK	I	Coick
P6	VSS	S	Supply Voltage Ground
P7	DAT0	I/O/PP	Date Line(bit0)
P8	DAT1	I/O/PP	Date Line(bit1)
P9	CD		CARD DETECT
P10	GND		GROUND

GENERAL TOLERANCE		KINGCONN 皇海科技股份有限公司	
X± 0.50	X*± 5 °	名 稱(TITLE) MICRO SD H1.45mm 推桿式	
.X± 0.30	.X*± 2 °		
.XX± 0.20	.XX*± 1 °		
單位(UNIT) mm	料 號(PART NO.) 7MSDP-F0-0036	圖 號(DWG NO.) 7MSDP-F0-0036	比例(SCALE) 1:1
審核(APPROVAL)	核 對(CHECKED)	製 圖(DRAWN)	圖 數(SHEET) 1/1
			更改(REV) A



更改	REV	数量	变更
A		ECXXXX	



SECTION A-A

SECTION B-B

备注:
1. 材质: 铝合金
2. 表面光滑无毛刺

建议机壳开孔尺寸



GENERAL TOLERANCE		KINGCONN 皇海科技股份有限公司	
X± 0.50	X*± 5 °	名 称(TITLE) MICRO SD H1.45mm 推棒式	
.X± 0.30	.X*± 2 °		
.XX± 0.20	.XX*± 1 °		
单 位(UNIT) mm	料 号(PART NO.) 7MSDP-F0-0036	图 纸(DWG NO.) 7MSDP-F0-0036	
审 核(APPROVAL)	核 对(CHECKED)	製 图(DRAWN)	分 数 SCALE 1:1
			张 数 SHEET 2 / 2
			更 改 REV A